

EAST - [10611390.wsp.1]

File View Edit Tools Window Help

Drafts  
 Pending  
 Active  
 L11: (8438) stack\$2 and semiconductor ar  
 L12: (1705) 11 and solder near ball\$1  
 L13: (1001) 12 and adhesive and contact  
 L14: (915) 13 and (hole\$1 via\$1)  
 L15: (551) 14 and ("BGA" ball adj grid adj  
 L16: (533) 15 and conductive  
 Failed  
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DBs: USPAT, US-PGPUB, EPO, JPO

Default operator: OR

Plurals  
 Highlight all hit terms initially

14 and ("BGA" ball adj grid adj array\$1)

BRST... ISAR... Image Text HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20040113275 A1	20040617	47	Semiconductor multi-package module having inverted second package stacked	257/758	
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20040113271 A1	20040617	33	Tape carrier package having stacked semiconductor elements, and short and	257/735	
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20040113255 A1	20040617	46	Semiconductor multi-package module having inverted second package and	257/686	438/109
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20040113254 A1	20040617	47	Semiconductor multi-package module having inverted second package stacked	257/686	257/659; 257/728;
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20040113253 A1	20040617	46	Semiconductor stacked multi-package module having inverted second package	257/686	
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20040113246 A1	20040617	22	Method of packaging at a wafer level	257/678	
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20040110366 A1	20040610	41	Forming solder balls on substrates	438/613	228/248.1; 228/41
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20040106229 A1	20040603	22	Methods for assembling multiple semiconductor devices	438/106	438/108; 438/612
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20040104486 A1	20040603	22	Electronic apparatus having an adhesive layer from wafer level packaging	257/778	257/782; 257/783;
10	<input type="checkbox"/>	<input type="checkbox"/>	US 20040104463 A1	20040603	16	Crack resistant interconnect module	257/686	
11	<input type="checkbox"/>	<input type="checkbox"/>	US 20040104408 A1	20040603	11	Stackable ceramic FBGA for high thermal applications	257/200	